

ENGINEERING DEPT.	PRODUCT SPECIFICATION For Right Angle Dip D-Sub Connector of system CD61	SPEC.NO.: SPCD032C
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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202

Methods for test of connectors for electronic equipment

MIL - STD - 1344

Test methods for electrical connectors

SS-00254

Test methods for electronic components , LEAD-FREE soldering Part
design standards

3. APPLICABLE SERIES NO.: **CD61 Series**

4. SHAPE,CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

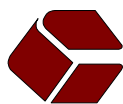
See attached drawings

6. ACCOMMODATED P.C.BOARD

1.6 mm (.063")



REVIEWED : ALEX APPROVED : Eisley VERIFIED : Bill .



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7. ELECTRICAL PERFORMANCE:

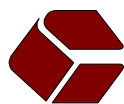
	ITEM	TEST CONDITION	
7.1	Rated current and voltage		3A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 5000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION		REQUIREMENT
8.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute from housing		More than 2.5 Kgf
8.2	Single contact insertion force	Measure force to insertion using Ø 1.04 mm test pin at speed 25± 3 mm per minute		340 gram max.
8.3	Single contact withdrawal force	Measure force to withdrawal using Ø 0.99 mm test pin at speed 25± 3 mm per minute		28 gram min.
8.4	Durability	Connector shall be subjected to 60 or 1000 cycles of insertion and withdrawal at speed 25± 3 mm per minute.	Gold flash : 600 cycles 15u''&30u'' gold plated: 1000 cycles	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solderability	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5°C Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5°C	Minimum: 90% of immersed area



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	ITEM	TEST CONDITION	REQUIREMENT
9.4	Resistance to soldering heat	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: $240 \pm 5^{\circ}\text{C}$ Lead-Free Process Soldering time: 5 ± 0.5 second Soldering pot: $260 \pm 5^{\circ}\text{C}$	No damage
9.5	Heat aging	$105 \pm 2^{\circ}\text{C}$, 96 hours	No damage
9.6	Humidity	$40 \pm 2^{\circ}\text{C}$, 90-95% RH , 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.7	Temperature cycling	One cycle consists of : (1) $-55^{+0}_{-3}^{\circ}\text{C}$, 30 min. (2) Room temp. 10-15 min. (3) $85^{+3}_{-0}^{\circ}\text{C}$, 30 min. (4) Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.8	Salt spray	Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE:

-40 to $+105^{\circ}\text{C}$; $+215^{\circ}\text{C}$ intermittent (Vapor Phase Solder Reflow) for SMT type

11. MATING FORCE AND UNMATING FORCE:

Unit: Kgf

No. of Circuits	Mating Force (Initial max.)	Unmating Force (Initial max.)
9	4.6	3.5
15	8.1	6.4
25	10.5	7.7
37	14.1	9.9